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# EUROPEAN STANDARD NORME EUROPÉENNE EUROPÄISCHE NORM

## EN 61249-5-1

January 1996

#### ICS 31.180

Descriptors: Printed circuits, interconnection structures, conductive foils and films, coatings, copper-clad base materials, flexible materials

English version

## Materials for interconnection structures Part 5: Sectional specification set for conductive foils and films with and without coatings Section 1: Copper foils (for the manufacture of copper-clad base materials) (IEC 1249-5-1:1995)

Matériaux pour les structures d'interconnexion Partie 5: Collection de spécifications intermédiaires pour feuilles et films conducteurs avec ou sans revêtement Section 1: Feuilles de cuivre (pour la fabrication de matériaux de base plaqués cuivre) (CEI 1249-5-1:1995) Materialien für Verbindungsstrukturen Teil 5: Rahmenspezifikation für leitfähige Folien und Filme mit und ohne Beschichtungen Hauptabschnitt 1: Kupferfolien (zur Herstellung von kupferkaschierten Basismaterialien) (IEC 1249-5-1:1995)

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European Committee for Electrotechnical Standardization Comité Européen de Normalisation Electrotechnique Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

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### Foreword

The text of document 52/544/DIS, future edition 1 of IEC 1249-5-1, prepared by IEC TC 52, Printed circuits, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 61249-5-1 on 1995-11-28.

The following dates were fixed:

<ul> <li>latest date by which the EN has to be implemented</li> </ul>		
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- latest date by which the national standards conflicting		

 latest date by which the national standards conflicting with the EN have to be withdrawn
 (dow) 1996-09-01

Annexes designated "normative" are part of the body of the standard. Annexes designated "informative" are given for information only. In this standard, annex A is normative and annex B is informative.

The following publication is quoted in this standard:

ISO 4287-1:1984 - Surface roughness - Terminology - Part 1: Surface and its parameters.

### **Endorsement** notice

The text of the International Standard IEC 1249-5-1:1995 was approved by CENELEC as a European Standard without any modification.

# NORME INTERNATIONALE INTERNATIONAL **STANDARD**

CEI IEC 1249-5-1

Première édition First edition 1995-11

### Matériaux pour les structures d'interconnexion -

### Partie 5:

Collection de spécifications intermédiaires pour feuilles et films conducteurs avec ou sans revêtement -Section 1: Feuilles de cuivre (pour la fabrication de matériaux de base plaqués cuivre)

### Materials for interconnection structures -

### Part 5:

Sectional specification set for conductive foils and films with and without coatings -Section 1: Copper foils (for the manufacture of copper-clad base materials)

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